



## Material Content Data Sheet



<b>Sales Product Name</b>	TLE75602-ESH			<b>Issued</b>	4. March 2019			
<b>MA#</b>	MA001709386							
<b>Package</b>	PG-TSDSO-24-21			<b>Weight*</b>	112.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27600	27600
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11292	
wire	non noble metal	copper	7440-50-8	51.392	45.85	47.05	458501	470499
	non noble metal	copper	7440-50-8	0.939	0.84	0.84	8375	8375
	organic material	carbon black	1333-86-4	0.150	0.13		1342	
encapsulation	plastics	epoxy resin	-	5.865	5.23		52328	
	inorganic material	silicondioxide	60676-86-0	44.114	39.36	44.72	393576	447246
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25160	25160
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11411	11411
glue	plastics	epoxy resin	-	0.190	0.17		1699	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8010	9709
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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